What is claimed is:

1. A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid.

2. The heat-resistant film according to claim 1, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.

3. The heat-resistant film according to claim 1, wherein the binder is polymethylmethacrylate.

4. The heat-resistant film according to claim 1, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

5. The heat-resistant film according to claim 1, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

6. The heat-resistant film according to claim 2, wherein the binder is polymethylmethacrylate.

7. The heat-resistant film according to claim 2, wherein the

heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

8. The heat-resistant film according to claim 2, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

9. The heat-resistant film according to claim 3, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

10. The heat-resistant film according to claim 3, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

11. The heat-resistant film according to claim 4, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

12. The heat-resistant film according to claim 6, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

13. The heat-resistant film according to claim 6, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

14. The heat-resistant film according to claim 7, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

15. The heat-resistant film according to claim 9, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

16. The heat-resistant film according to claim 11, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

17. A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid.

18. The thermal transfer recording medium according to claim 17, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.

19. The thermal transfer recording medium according to claim 17, wherein the binder is polymethylmethacrylate.

20. The thermal transfer recording medium according to claim 17, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

21. The thermal transfer recording medium according to claim 17, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.